TOSHIBA Photocoupler GaAlAs Ired + Photo IC

# **TLP751**

**Digital Logic Ground Isolation** Line Receiver Microprocessor System Interfaces Switching Power Supply Feedback Control **Analog Signal Isolation** 

The TOSHIBA TLP751 consists of GaAlAs high-output light emitting diode and a high speed detector of one chip photo diodetransistor. This unit is 8-lead DIP.

TLP751 has internal base connection. This base pin should be used for analog application or enable operation. If base pin is open, output signal will be noisy by environmental condition. For this case, TLP750 is suitable.

- Switching speed:  $t_{pHL} = 0.3 \mu s$  (typ.)  $t_{pLH} = 0.5\mu s \text{ (typ.)}(R_L=1.9k\Omega)$
- TTL compatible
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 1994,

Isolation voltage: 5000Vrms(min.)

Certificate no. 7613 BS EN60950: 1992.

- Certificate no. 7614
- Option(D4)type

VDE approved: DIN VDE0884 / 06.92,

Certificate no. 68384

Maximum operating insulation voltage: 890VPK

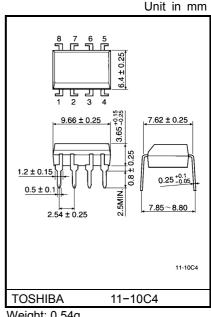
Highest permissible over voltage: 8000VPK

### (Note) When a VDE0884 approved type is needed, please designate the "Option(D4)"

Creepage distance: 6.4mm(min.)

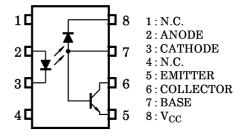
Clearance: 6.4mm(min.)

Insulation thickness: 0.4mm(min.)

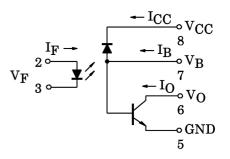


Weight: 0.54g

### Pin Configuration(top view)



#### **Schematic**



## **Maximum Ratings (Ta = 25°C)**

	Characteristic		Symbol	Rating	Unit
TED	Forward current	(Note 1)	lF	25	mA
	Pulse forward current	(Note 2)	I <sub>FP</sub>	50	mA
	Peak transient forward current	(Note 3)	I <sub>FPT</sub>	1	А
	Reverse voltage		V <sub>R</sub>	5	V
	Diode power dissipation	(Note 4)	P <sub>D</sub>	45	mW
Detector	Output current		IO	8	mA
	Peak output current		l <sub>OP</sub>	16	mA
	Output voltage		Vo	-0.5~15	V
	Supply voltage		V <sub>CC</sub>	-0.5~15	V
	Base current		ΙΒ	5	mA
	Output power dissipation	(Note 5)	Po	100	mW
	Emitter-base reverse voltage		V <sub>EB</sub>	5	V
Оре	Operating temperature range		T <sub>opr</sub>	-55~100	°C
Sto	Storage temperature range		T <sub>stg</sub>	-55~125	°C
Lea	Lead solder temperature(10s) (Note 6)		T <sub>sol</sub>	260	°C
	Isolation voltage (AC,1min.,R.H.≤ 60%) (Note 7)		BVS	5000	Vrms

(Note 1) Derate 0.8mA above 70°C

(Note 2) 50% duty cycle,1ms pulse width.

Derate 1.6mA / °C above 70°C

(Note 3) Pulse width  $\leq 1\mu s$ ,300pps.

(Note 4) Derate 0.9mW / °C above 70°C

(Note 5) Derate 2mW / °C above 70°C

(Note 6) Soldering portion of lead : up to 2mm from the body of the device.

(Note 7) Device considered a two terminal device: Pins 1,2,3 and 4 shorted together and pins 5,6,7 and 8 shorted together.

# Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit	
LED	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 16 mA	_	1.65	1.85	V	
	Forward voltage Temperature coefficient	ΔV <sub>F</sub> / ΔTa	I <sub>F</sub> = 16 mA	_	-2	_	mV / °C	
	Reverse current	$I_{R}$	V <sub>R</sub> = 5 V	_	_	10	μΑ	
	Capacitance between terminal	СТ	V <sub>F</sub> = 0, f = 1 MHz	_	45	_	pF	
Detector	High level output current	I <sub>OH</sub> (1)	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	_	3	500	nA	
		I <sub>OH</sub> (2)	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 15 V	_	_	5		
		Іон	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 15 V	_	_	50	μА	
			Ta = 70°C					
	High level supply voltage	I <sub>CCH</sub>	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = 15 V	_	0.01	1	μΑ	
Coupled	Current transfer ratio	I <sub>O</sub> / I <sub>F</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V	10	30	_	%	
			V <sub>O</sub> = 0.4 V	10				
	Low level output voltage	V <sub>OL</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V		_	0.4	V	
			I <sub>O</sub> = 1.1 mA	_				
	resistance(input-output)	R <sub>S</sub>	R.H. ≤ 60%, V <sub>S</sub> = 500 V <sub>DC</sub> (Note7)	1×10 <sup>12</sup>	10 <sup>14</sup>	_	Ω	
	Capacitance (input-output)	C <sub>S</sub>	V <sub>S</sub> = 0, f = 1 MHz (Note7)	_	0.8	_	pF	

# Switching Characteristics (Ta = 25°C, $V_{CC} = 5V$ )

Characteristic		Symbol	Test Cir- cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time (H→L)		t <sub>pHL</sub>	1	$I_F = 0 \rightarrow 16$ mA, $V_{CC} = 5$ V, $R_L = 4.1$ kΩ	-	0.2	_	μs
Propagation delay time (L→H)		t <sub>pLH</sub>		$I_F$ = 16→0mA $V_{CC}$ = 5V, $R_L$ = 4.1 kΩ	_	1.0	_	μs
Common mode transient immunity at logic high output	(Note 8)	CM <sub>H</sub>		$I_F = 0 \text{ mA}, V_{CM} = 200 V_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	1	400	ı	V / µs
Common mode transient immunity at logic low output	(Note 8)	CML	2	$I_F = 16 \text{ mA}$ $V_{CM} = 200 V_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	_	-1000	_	V / µs

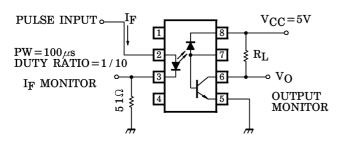
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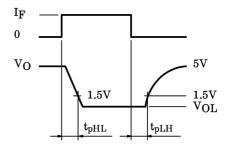
(Note 8) CM<sub>L</sub> is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state( $V_Q < 0.8V$ ).

 $CM_H$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state( $V_Q > 2.0V$ ).

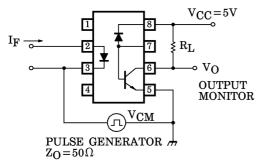
(Note 9) Maximum electrostatic discharge voltage for any pins: 100V (C = 200pF, R = 0).

## **Test Circuit 1: Switching Time Test Circuit**

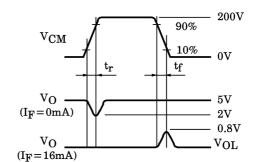


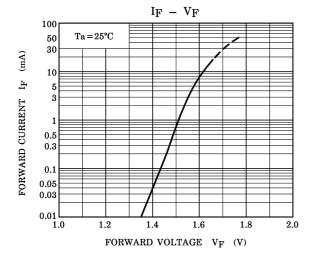


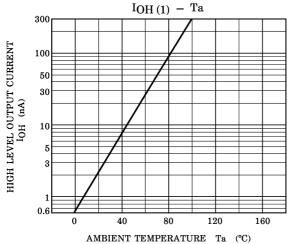
### **Test Circuit 2: Common Mode Noise Immunity Test Circuit**

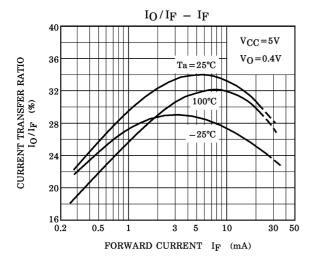


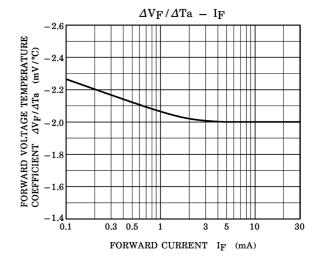
$$\text{CM}_H = \frac{160 \, \text{(V)}}{t_r \, (\mu \text{s})}$$
 ,  $\text{CM}_L = \frac{160 \, \text{(V)}}{t_f \, (\mu \text{s})}$ 

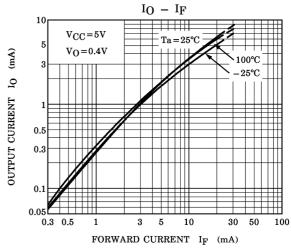


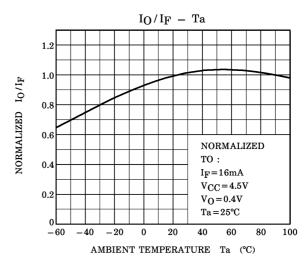




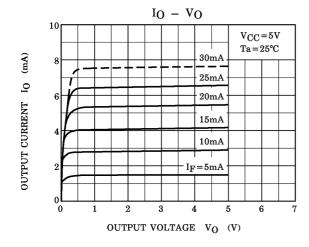


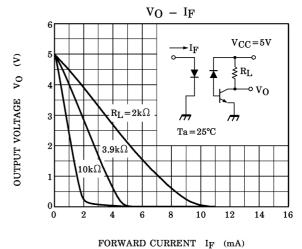






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